

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	375	257/725.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2008/08/01 08:07
L8	35235	sip "system-in-package" "system-in-a- package" (system near2 package)	US-PGPUB; USPAT	OR	ON	2008/08/01 08:16
L9	83	L8 same (capacit\$6 near coupl\$6)	US-PGPUB; USPAT	OR	ON	2008/08/01 08:16
L10	151	L8 and ((capacit\$6 near coupl\$6) same (guard\$6 ring\$6 ground\$6))	US-PGPUB; USPAT	OR	ON	2008/08/01 08:23
L11	8863	257/723.ccls. 257/725. ccls. 257/777.ccls. 257/786.ccls. 257/ E23.02.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2008/08/01 08:33
L12	467	L11 and (sip "system-in- package" "system-in-a- package" (system near2 package))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/01 08:33
L13	16	L12 and (capacit\$6 near coupl\$6)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/01 08:33
L14	57	L11 and ((capacit\$6 near coupl\$6) same (guard\$6 ring\$6 ground\$6))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/01 08:36
L15	11431	sip "system-in-package" "system-in-a- package" (system near2 package)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/01 08:40
L16	12	L15 and (capacit\$6 near coupl\$6)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/01 08:40
L17	4	L15 and ((guard\$6 ground\$6) with ring\$6)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/01 08:44
L18	3132	(capacit\$6 near coupl\$6) and (guard\$6 ring\$6 ground\$6)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/01 08:45

L19	1123	L18 and (semiconductor wafer substrate integrated ic chip die dice)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/01 08:45
L20	64	L19 and (packag\$6 encapsulat\$6)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/01 08:45
L21	8353	((sip "system-in-package" "system-in-a-package" (system near2 package) transmi\$8 receiv\$6 signal\$6) and (capacit\$6 near2 (coupl\$6 communicat\$6)) and (guard\$6 ring\$6 ground\$6)).clm.	US-PGPUB; USPAT	OR	ON	2008/08/01 08:55
L22	14	((sip "system-in-package" "system-in-a-package" (system near2 package)) and (transmi\$8 receiv\$6 signal\$6) and (capacit\$6 near2 (coupl\$6 communicat\$6)) and (guard\$6 ring\$6 ground\$6)).clm.	US-PGPUB; USPAT	OR	ON	2008/08/01 08:56
L23	738	((sip "system-in-package" "system-in-a-package" (system near2 package) ((semiconductor device component chip die dice) near4 (first second two another other))) and (transmi\$8 receiv\$6 signal\$6) and (capacit\$6 near2 (coupl\$6 communicat\$6)) and (guard\$6 ring\$6 ground\$6)).clm.	US-PGPUB	OR	ON	2008/08/01 08:59
L24	348	((sip "system-in-package" "system-in-a-package" (system near2 package) ((semiconductor device component chip die dice) near2 (first second two another other))) and (transmi\$8 receiv\$6 signal\$6) and (capacit\$6 near2 (coupl\$6 communicat\$6)) and (guard\$6 ring\$6 ground\$6) and (pad electrode	US-PGPUB	OR	ON	2008/08/01 09:01

		terminal land\$6)).cm.				
L25	135	((sip "system-in-package" "system-in-a-package" (system near2 package) ((semiconductor device component chip die dice) near2 (first second two another other))) and (transmi\$8 receiv\$6 signal\$6) and (capacit\$6 near2 (coupl\$6 communicat\$6)) and (guard\$6 ring\$6 ground \$6) and (pad electrode terminal land\$6) and (dielectric insulat\$6 separat\$6 spac\$6 oxide dioxide nitride)).cm.	US-PGPUB	OR	ON	2008/08/01 09:03
L26	46	((sip "system-in-package" "system-in-a-package" (system near2 package) ((semiconductor device component chip die dice) near2 (first second two another other))) and ((transmi\$8 receiv\$6 signal\$6) with (capacit\$6 near2 (coupl\$6 communicat\$6)) and (guard\$6 ring\$6 ground \$6) and (pad electrode terminal land\$6) and (dielectric insulat\$6 separat\$6 spac\$6 oxide dioxide nitride)).cm.	US-PGPUB	OR	ON	2008/08/01 09:04

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